TAZMO

Q1 FY2026 Financial Announcement

January – March 2026

May 15, 2026

Security Code: 6266

Company Guide

https://tazmo.co.jp/wp/wp-content/uploads/2025/11/company%20guide.pdf

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Q1 FY2026 Consolidated Financial Summary

Q1 FY2026 Financial Highlights

Net sales	Operating income	Ordinary income	Net income(*)
5,967	**86**	**186**	**111**
Million Yen	Million Yen	Million Yen	Million Yen
YoY Change △20.6 %	YoY Change △92.9 %	YoY Change △84.1 %	YoY Change △87.0 %

■ Overview

- ■ Revenue and profit both declined year on year. Sales fell short of the plan in the semiconductor equipment, material handling equipment, and surface treatment equipment businesses; however, profit was broadly in line with the plan.
- ■ We achieved a significant increase in order intake for semiconductor manufacturing equipment and material handling systems. While the overall market is on a recovery trend amid improving conditions, there are substantial disparities among businesses in both the volume of orders and the timing of their receipt.

(*) Net income: Net income attributable to owners of parent

Q1 FY2026 Financial Summary

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(Millions of yen)	FY2025 Q1	FY2026 Q1		YoY change (%)	FY2026 estimates	cf. Plan
		Actual	Net sales ratio (%)			
Net sales	7,516	5,967	-	△20.6	35,500	16.8
Gross profit	2,606	1,624	27.2	△37.7	-	-
Operating income	1,210	86	1.4	△92.9	3,600	2.4
Ordinary income	1,176	186	3.1	△84.1	3,500	5.3
Net income attributable to owners of parent	855	111	1.9	△87.0	2,500	4.5

Trend in Net sales and Operating profit

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Balance Sheet

(Millions of yen)	FY2025 Actual	FY2026 Q1	YoY change
Current assets	37,809	36,605	△1,204
Non-current assets	9,083	9,456	373
Property, plant and equipment	7,812	8,178	366
Intangible assets	199	196	△3
Investments and other assets	1,070	1,081	10
Total assets	**46,893**	**46,062**	**△830**
Current Liabilities	14,393	12,964	△1,428
Non-Current Liabilities	5,462	6,337	874
Total liabilities	**19,855**	**19,302**	**△553**
Total net assets	**27,037**	**26,760**	**△277**
Equity ratio	56.6%	57.0%	0.4P

Major change

Current Assets

(Millions of yen)

Item	Change
Cash and deposits	△808
Notes and accounts receivable - trade	+145
Electronically recorded monetary claims - operating	△195
Inventories	△260

Current Liabilities

Item	Change
Electronically recorded obligations - operating	△1,728
Non trade payables	△570
Income taxes payable	△700
Contract liabilities	+1,122

Non-Current Liabilities

Item	Change
Long-term borrowings	+828

Balance Sheet

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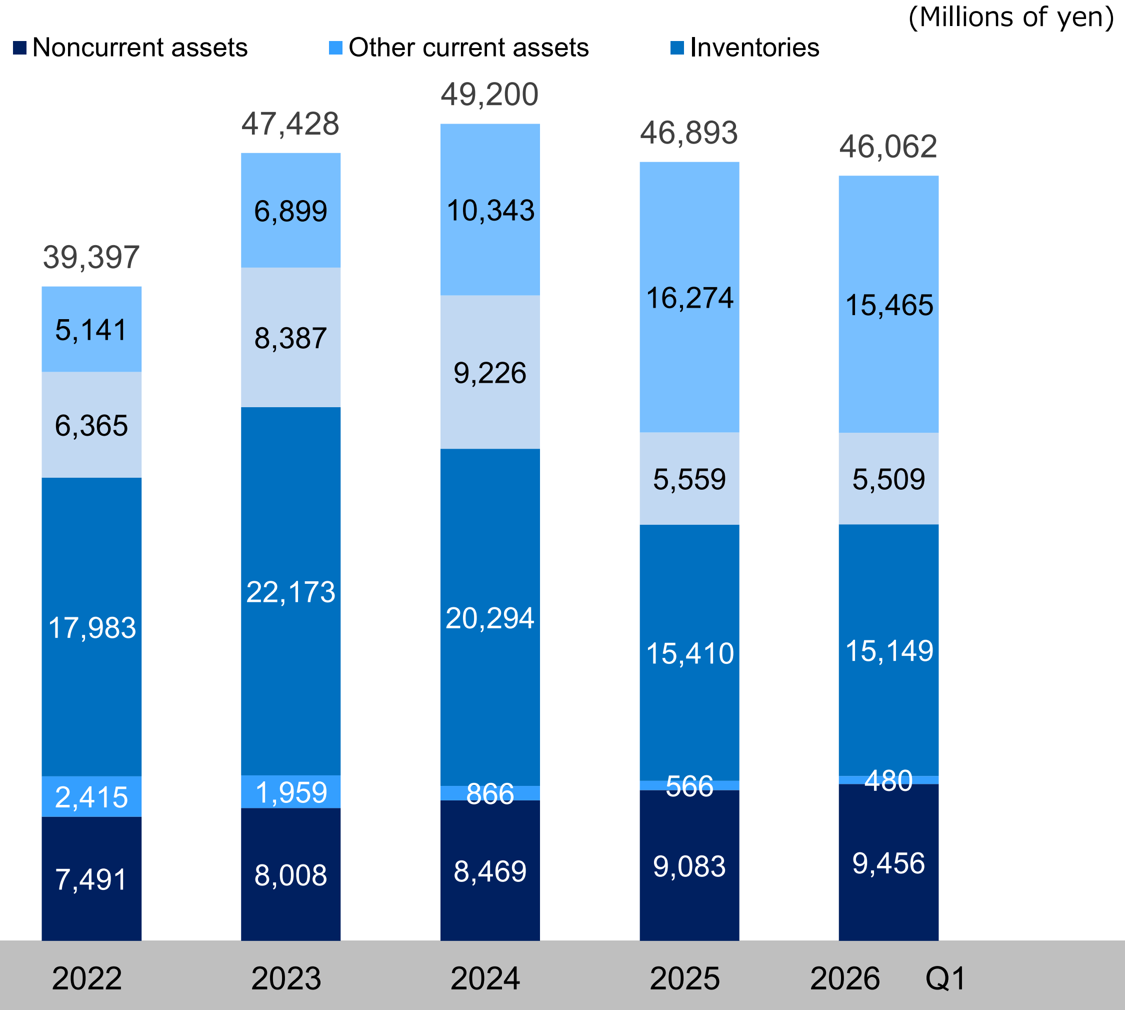
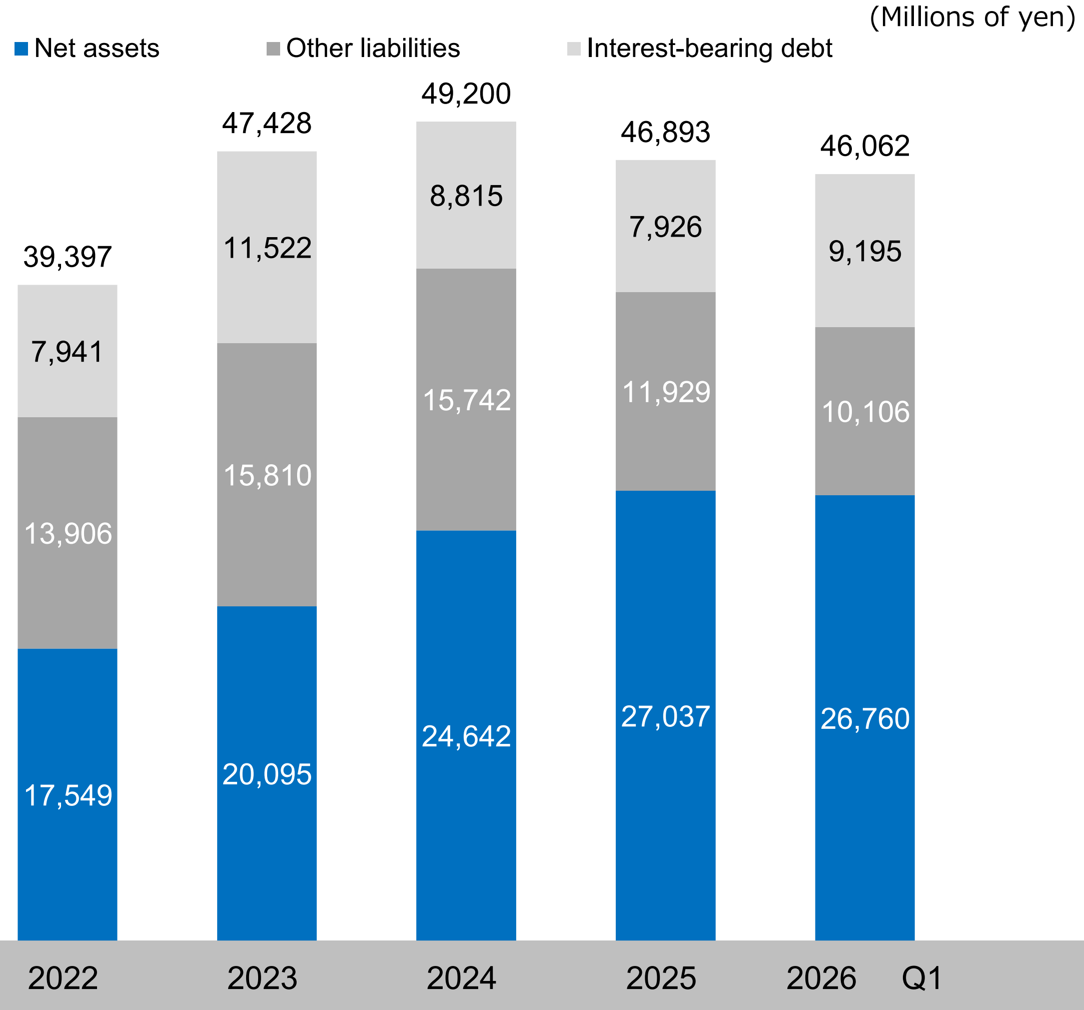
Assets



Liabilities/Equity



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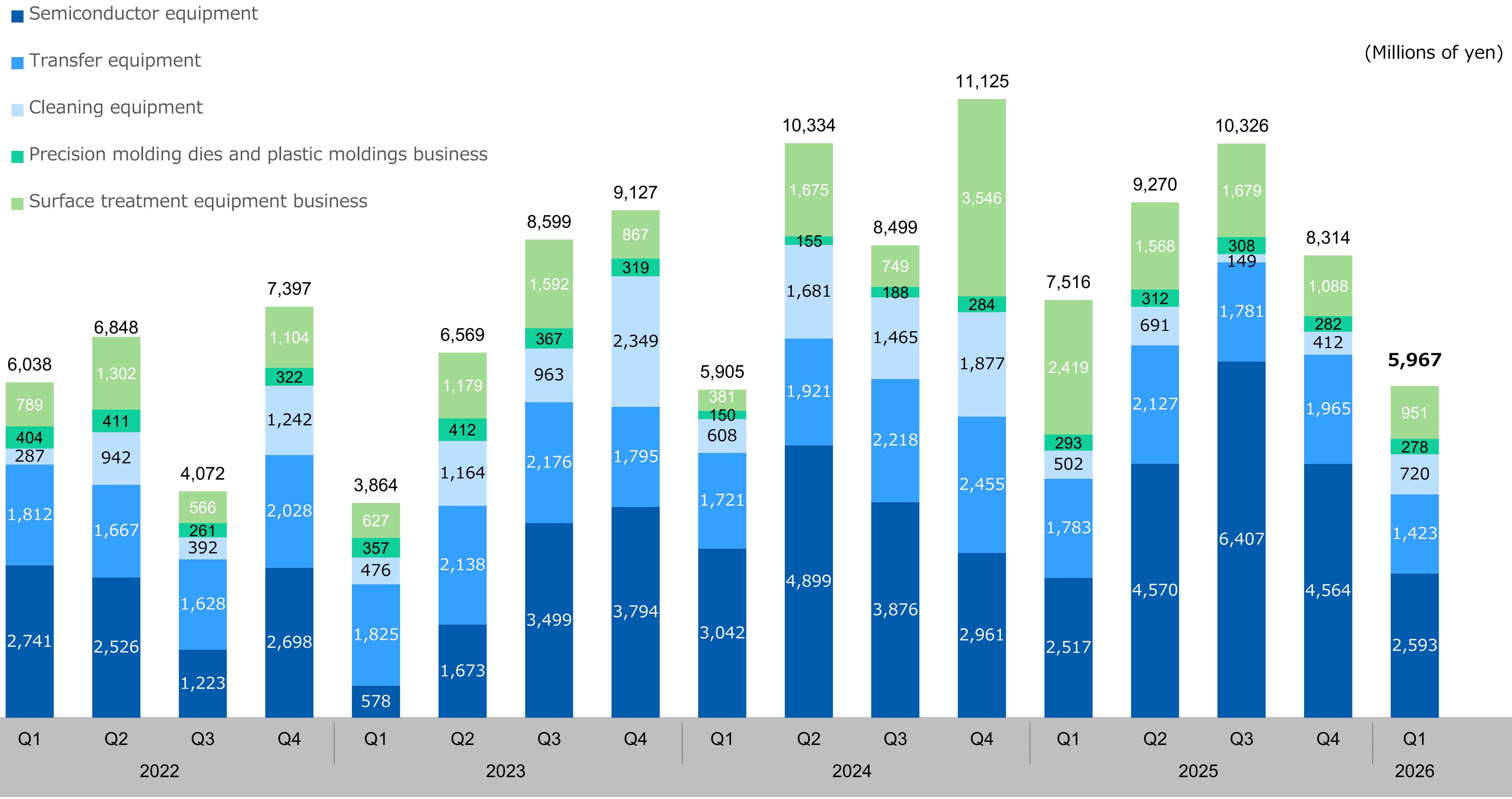
Q1 FY2026 Segment Information

Net Sales and Operating Profit by Segment

(Millions of yen)

		FY2025 Actual	FY2026 Q1 Actual	YoY change(%)	FY2026 Initial estimates	cf. Plan (%)
Process equipment business	Net sales	4,803	4,737	△1.4	29,700	15.9
	Operating income	752	60	△92.0	3,400	1.8
■ Semiconductor equipment	Net sales	2,517	2,593	3.0	18,500	14.0
■ Transfer equipment	Net sales	1,783	1423	△20.2	8,860	16.1
■ Cleaning equipment	Net sales	502	720	43.4	2,340	30.8
Precision molding dies and plastic moldings business	Net sales	293	278	△5.2	1,300	21.4
	Operating income	38	△0	-	70	-
Surface treatment equipment business	Net sales	2,419	951	△60.7	4,500	21.1
	Operating income	394	14	△96.3	130	10.8
Elimination of inter-segment transactions	Operating income	△95	12	-	-	-
Total	Net sales	7,516	5,967	△20.6	35,500	16.8
	Operating income	1,210	86	△92.9	3,600	2.4

Trend in Net sales by Segment



Starting from the fiscal year ending December 2026, the business previously recorded under the "Coater" segment has been reclassified and reported in combination with the "Semiconductor Equipment" segment. Accordingly, past performance figures have also been restated under the same segment classification. For sales trends under the previous classification, please refer to the supplementary materials.

Trend in Sales Orders by Segment

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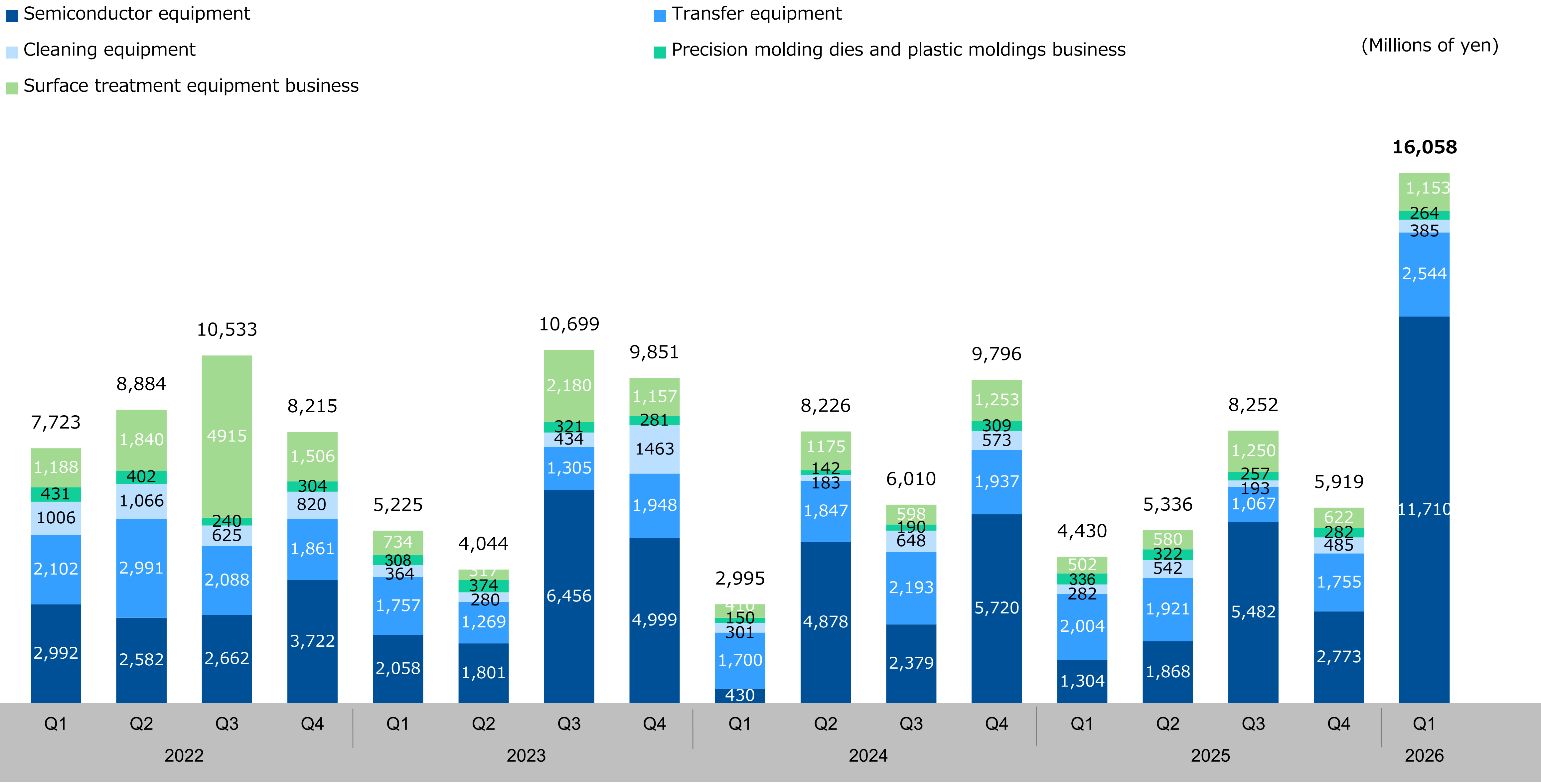

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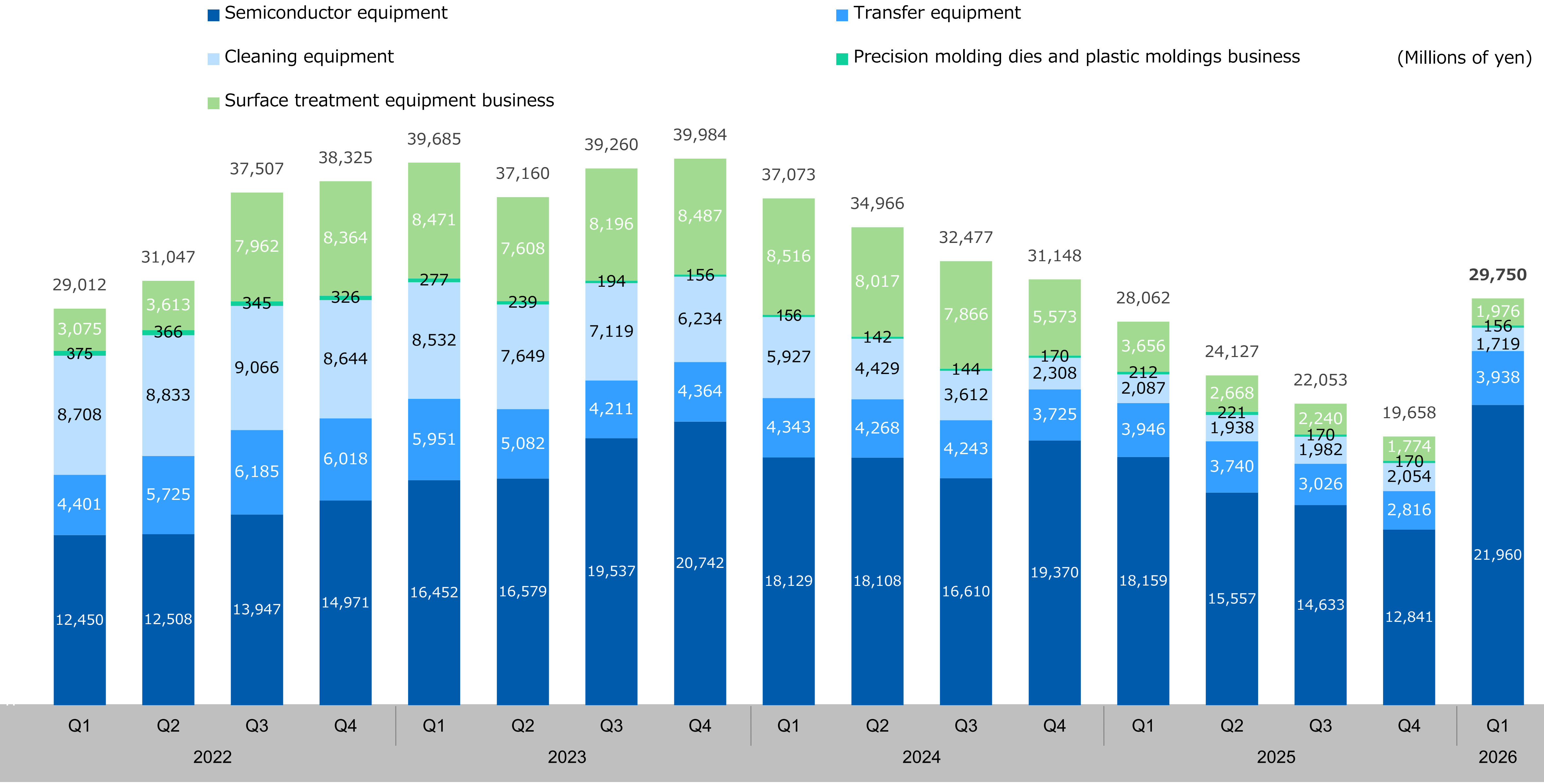
Trend in Order Backlog by Segment



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Business Environment

Business Environment

- In equipment for advanced packaging, we have been able to achieve a significant increase in orders. While future capital investment will be influenced to a large extent by market conditions, we continue to have expectations. In equipment for power semiconductors, customer inquiries are on an upward trend, and we aim to convert these inquiries into orders.

- For PLP equipment for advanced packaging, inquiries related to processes we have been working on to date—such as coating, debonding, and cleaning—are increasing. While the inquiries vary in size and scope, we are responding to them with the aim of securing orders with a high degree of certainty, and we expect the market to expand further.

- In material handling systems, inquiries have surged as capital investment has begun to recover, with demand related to PLP equipment also showing an upward trend. Many projects require short lead times, and combined with the lengthening lead times for components, this is making production scheduling increasingly challenging.

- For cleaning equipment, there are few discussions regarding new projects, and a recovery is likely to take some time. Inquiries for slurry supply systems are increasing; however, users' investment decisions are expected to require additional time.

- For surface treatment equipment, order intake and inquiries—particularly for substrate handling—are showing signs of recovery. We look forward to securing orders associated with upcoming capital investment projects.

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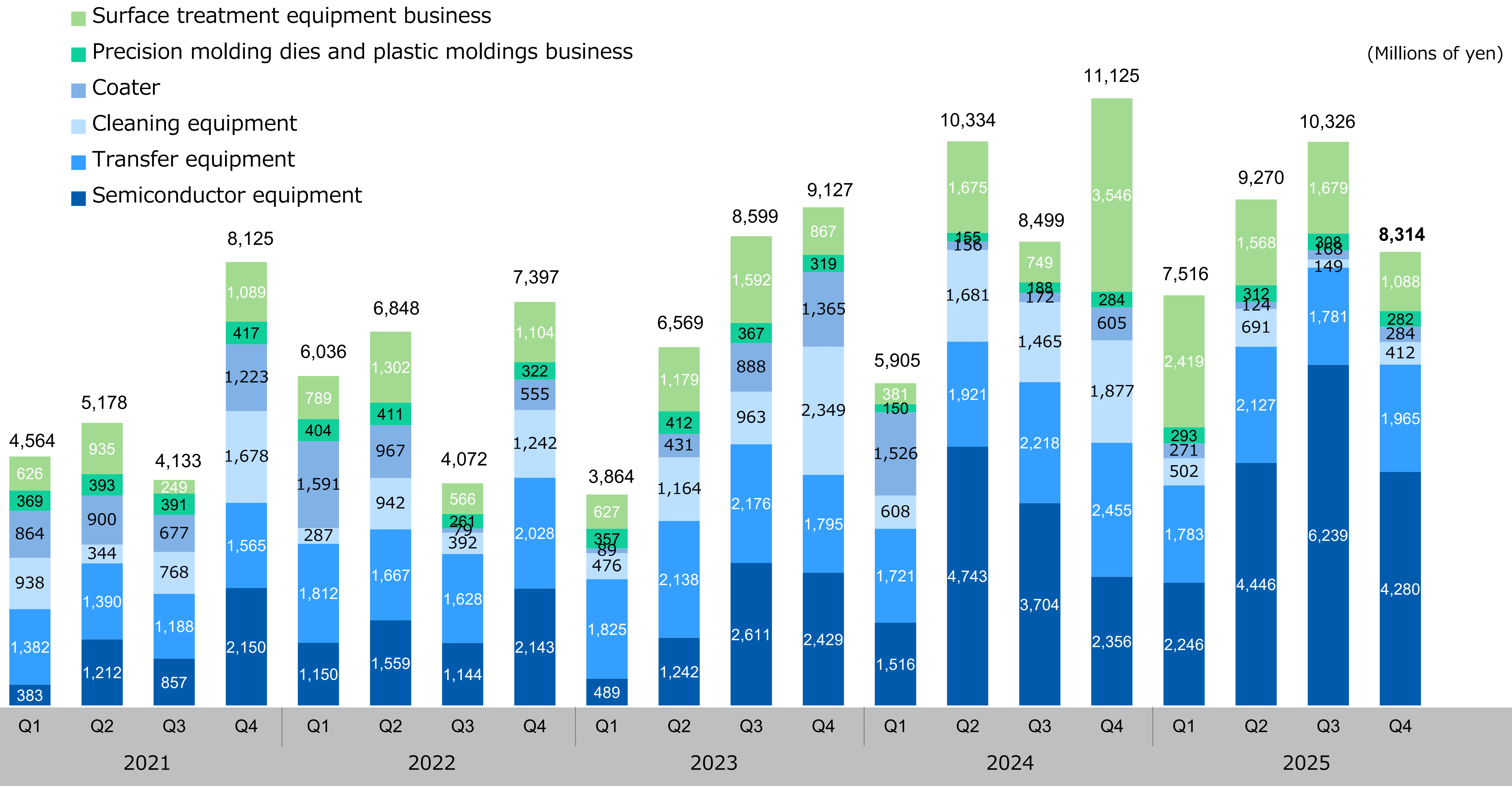
Appendix

Trend in Net sales by Conventional Segment(Quarter)



Trend in Sales Orders by Conventional Segment(Quarter)

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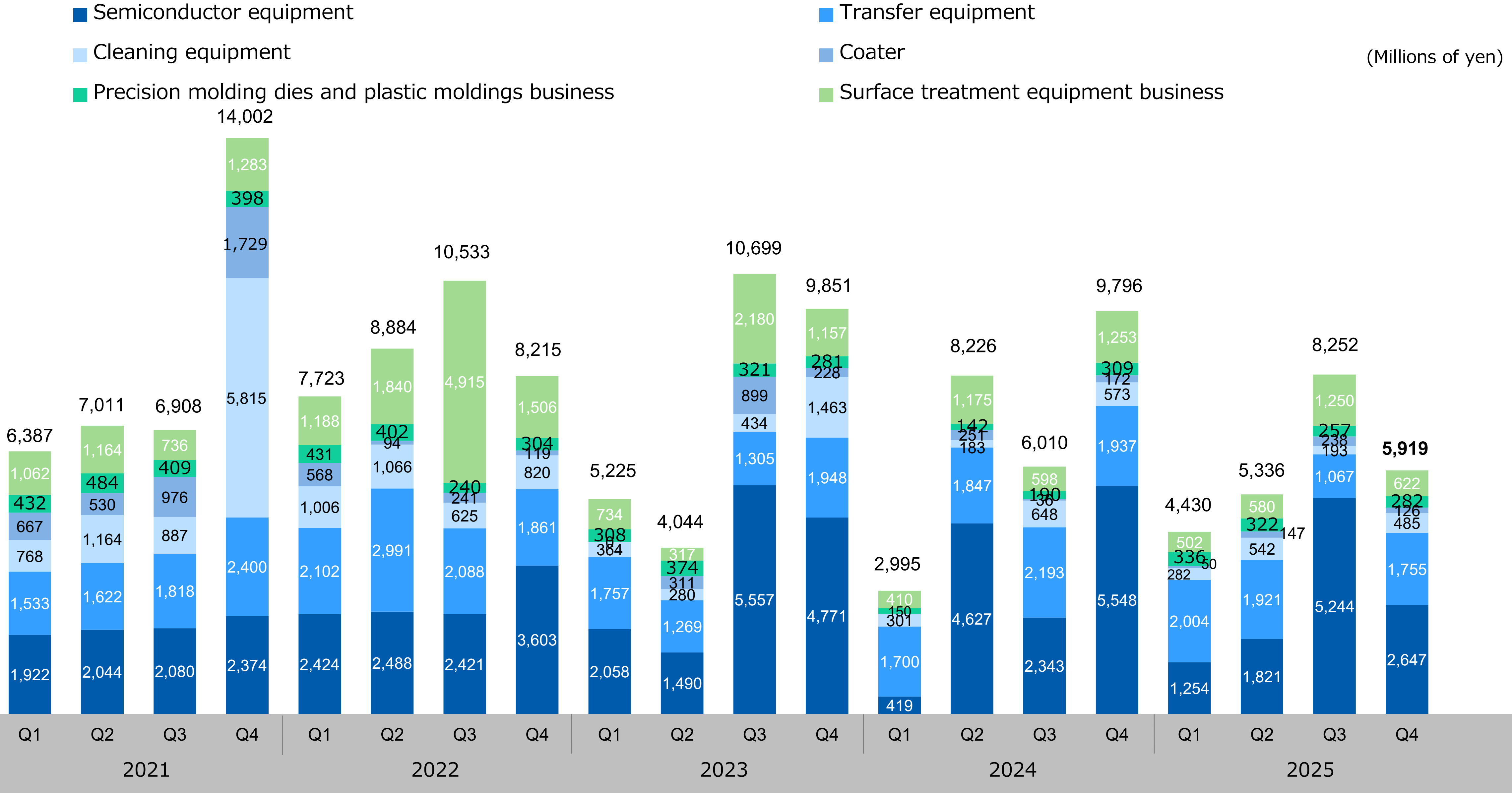
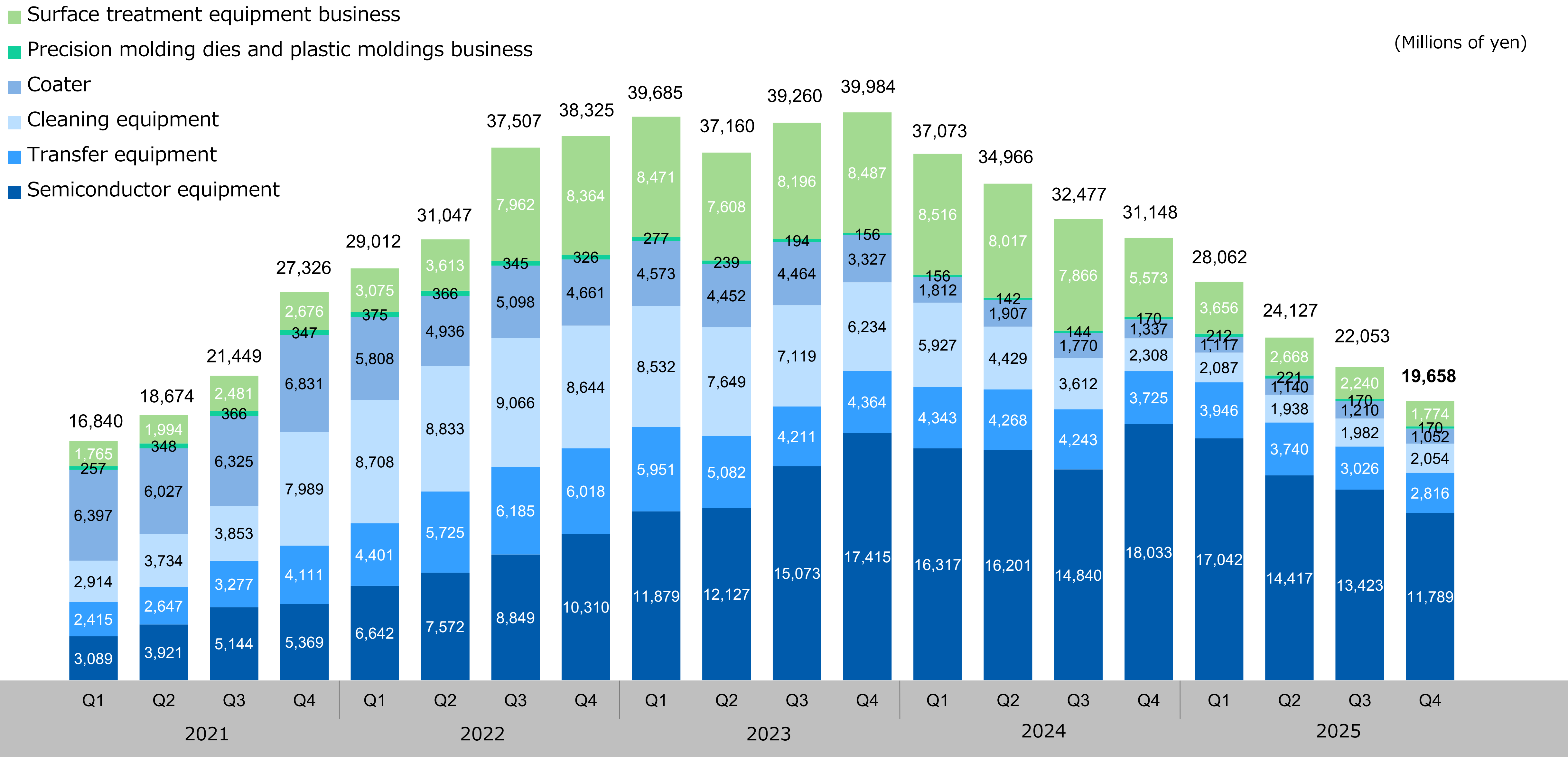


Trend in Order Backlog by Conventional Segment



Company Info

TAZMO

Company name	TAZMO Co., Ltd.
Established	February 26, 1972
Head office	5311, Haga, Kita-ku, Okayama-shi, Okayama 701-1221, Japan
Capital	3,556,890,682 yen
Total number of issued shares	14,842,354
Number of shareholders	9,433 (As of December 31, 2025)
Number of employees	Non-consolidated 449 Consolidated 1,150 (As of December 31, 2025)
Business content	Development, Manufacturing and Sales of Semiconductor Manufacturing Equipment, Clean Transfer System, LCD Manufacturing Equipment,UV Laser Equipment, Plating Equipment, Mold/Resin Molding, Plating/Circuit formation Equipment for PCB

Domestic locations, Subsidiaries

Okayama-shi, Okayama
Head office

Shinjuku-ku,Tokyo
Tokyo office

Ibara-shi, Okayama
TAZMO Plant No.1
TAZMO Plant No.3
TAZMO Plant No.5
Quark Technology Co., Ltd.
PRETEC Co., Ltd.

Global Network

Dongguan City,Guangdong Province, China
Facility Technology (Dongguan) Co., Ltd.

Taiwan
TAZMO Apprecia Formosa Inc.

Hong Kong
Facility (HK) Co., Ltd.

Shaoxing City, Zhejiang Province, China
TAZMO Semitec Shaoxing Technology Co., Ltd.

San Francisco
TAZMO INC.

Vietnam
TAZMO VIETNAM CO.,LTD.
FACILITY HANOI CO.,LTD.

Milestones

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1972	- TAZMO Co., Ltd. is incorporated to manufacture and produce electronic components and repair industrial equipment.
1980	- Began production of molding dies, including injection molding dies. - Completed development of Fully-automated Photo Resist Coater; production and sales started.
1989	- Developed TFT Full-color filter manufacturing system; production and sales started.
1990	- Constructed new head office/plant at 6186 Kinoko-Cho, Ibara, Okayama - Developed and produced Ultra Compact Transfer System for Super Clean Room.
1994	- Began production and sales of Emboss Carrier Tape.
1995	- Began production of injection Molding Products.
2001	- Developed “CS13” series Photo Resist Coater specialized for a thicker film application; production and sales started.
2004	- Listed on the JASDAQ market.
2008	- Established TAZMO VIETNAM CO., LTD. a consolidated subsidiary, in Ho Chi Minh City, Vietnam.
2009	- Developed 10th generation compatible full-color filter manufacturing system; production and sales started. - Concluded a license agreement with 3M(USA) for semiconductor manufacturing equipment.
2013	- Apprecia Technology Inc. became our wholly owned subsidiary company. - VIETNAM CO., LTD. Constructed new factory at Long Hau Industrial Park in Long An Province, Vietnam.
2017	- Facility Co., Ltd. and Quark Technology Co., Ltd. became our wholly owned subsidiary company.
2018	- Listed on the First Section of the Tokyo Stock Exchange
2019	- Constructed a new head office at 5311 Haga Kita-ku, Okayama-shi, Okayama
2020	- Merged with Apprecia Technology Inc.
2022	- TAZMO’s listing transferred to Prime Market in Tokyo Stock Exchange. - Increased capital to 3,495,400,000 yen through public offering. - Established TAZMO SEMITEC SHAOXING TECHNOLOGY Co., Ltd. a consolidated subsidiary, in Zhejiang Shaoxing, China.

Business Introduction

Semiconductor Manufacturing Equipment Business Unit

Bonder / Debonder

- For Advanced Packaging（WLP ※1／PLP ※2）
- For Power Semiconductors

We develop, design, manufacture, and sell temporary bonding and debonding systems that enable wafer thinning, an essential process for the production of high-performance chips.By bonding wafers to glass carrier substrates, our systems allow wafer thinning while preventing damage to the wafers.

Coater / Developer

Leveraging the expertise gained through the development and manufacturing of FPD production equipment, we enable uniform chemical coating and precise circuit formation by selectively removing only the exposed areas during the development process.

※1 WLP：Wafer-Level Packaging
※2 PLP ：Panel-Level Packaging

Transfer Business Unit

- For Semiconductor Equipment Manufacturers (Wafers, Masks, and Related Components)

We develop, design, manufacture, and sell transfer robots used in semiconductor manufacturing equipment, as well as EFEMs in which various units are integrated into frames.

Cleaner Business Unit

We develop, design, manufacture, and sell single-wafer cleaning systems for wafer manufacturers, as well as slurry supply systems and equipment that recovers and reuses phosphoric acid from waste liquids.

Surface Treatment Business

We provide plating systems for printed circuit boards used in semiconductor packages and electronic control systems for automobiles and other applications.

Molding Business

We provide precision molds and resin molded products for connector manufacturers.

Notes

Forward-looking statements with respect to TAZMO's business plan, prospects and other such information are based on information available at the time of publication. Actual performance and results may differ significantly from the business plan described here due to changes in various external and internal factors.

This material takes as its objective the provision of information regarding the management policy, plans, and financial situation of TAZMO to shareholders, investors and other visitors. It constitutes neither an offer nor a solicitation to purchase or sell TAZMO stock.

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